

RESIN COMPOSITION FOR ENCAPSULATION AND ELECTRONIC DEVICE USING THE
SAME

ABSTRACT

5

The present invention provides a resin composition for encapsulating electronic elements that contains a phenol resin curing agent, an epoxy resin, and a release agent of which a 5% weight reduction temperature is equal to or higher than 240°C; a resin composition for encapsulating electronic components that contains an epoxy resin and a release agent of which a 5% weight reduction temperature is equal to or higher than 240°C; and a resin composition for encapsulating electronic components that contains a phenol resin curing agent, an epoxy resin, and a release agent of which a 5% weight reduction temperature is equal to or higher than 240°C, in which a glass transition temperature (T_g) of a cured material of the encapsulating resin composition is equal to or higher than 200°C, and when the cured material is heated for 1,000 hours at 200°C in the atmosphere, a weight reduction rate of the cured material becomes equal to or lower than 0.3%; and an electronic device that includes an electronic component encapsulated with the resin composition.

10
15
20

[No Fig.]